

# BOOMPODS (HK) LTD.

RM 303-304 Hankow Centre 5-15, Hankow Road, T.S.T. Kowloon, Hongkong

## Declaration concerning Antenna Specification

It is hereby declared that the product

Model No.: BOOMBUDS

FCC ID: 2AFAX-BOOMBUDS

fulfills the requirement in FCC test relating to the antenna type.

The device specified above confirms to the FCC recommendations for integral antenna type(s) described below:

Model No. of antenna: LA52H2450-A36  
Type of antenna: Chip Antenna  
Gain of the antenna: Maximum 4.97 dBi  
Frequency range: 2402-2480MHz

The mounting of the antenna is fixed to the radio module and no other antenna should be used.

Company name: BOOMPODS (HK) LTD.


Address: RM 303-304 Hankow Centre 5-15, Hankow Road, T.S.T. Kowloon, Hongkong

City: Kowloon

ZIP / Postal code: N/A

Country: Hongkong

Place: Hongkong Date: 2018/07/18

Signature: 

# 产品技术规格书

## SPECIFICATION

|                             |
|-----------------------------|
| 产品型号 PART NO: LA52H2450-A36 |
| 客户料号 CUSTOMER PART NO:      |
| 客户确认 CUSTOMER APPROVED BY:  |
| 确认日期 APPROVED DATE:         |

|                 |                                   |                 |
|-----------------|-----------------------------------|-----------------|
| 拟制 Prepared by: | 审核 Checked by :                   | 批准 Approved by: |
| 送样日期 Formed On  | 产品版本 Document Version<br>( V1.0 ) |                 |

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## 产品规格书版本更改记录

## Version rejigger track record

| 版本号<br>Version  | 更改记录 Rejigger | 拟制<br>Prepared | 批准<br>Approve | 日期<br>Date   |
|---|---------------|----------------|---------------|--------------|
| V1.0  | 首次发行          | 蔡壮             | 陆德龙           | 2015. 12. 25 |
|   |               |                |               |              |
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|   |               |                |               |              |
| 备注：<br>1、更改产品电性能指标时，版本号需更换（V1.0 换为 V2.0、V3.0……）；<br>2、更改产品测试方法（包括可靠性测试条件），或更改使用条件时，当前版本号加系列（V1.0 换为 V1.1、V1.2……）。 |               |                |               |              |

## 1. 概述 INTRODUCTION

微波多层陶瓷天线 LA 系列产品设计用于 WLAN、WiFi、蓝牙、PHS，手机多频天线, FM 等小体积 SMD 片式设计。

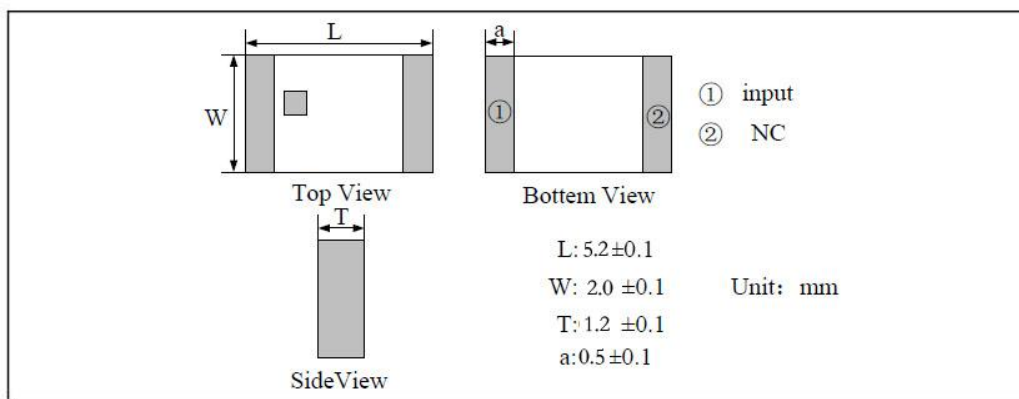
Microwave Multi -Layer Ceramic Antenna LA series are designed to be used in WLAN、WiFi、Bluetooth、PHS、 Multiple-band Mobile phone antenna, FM, etc and compact size SMD chip design.

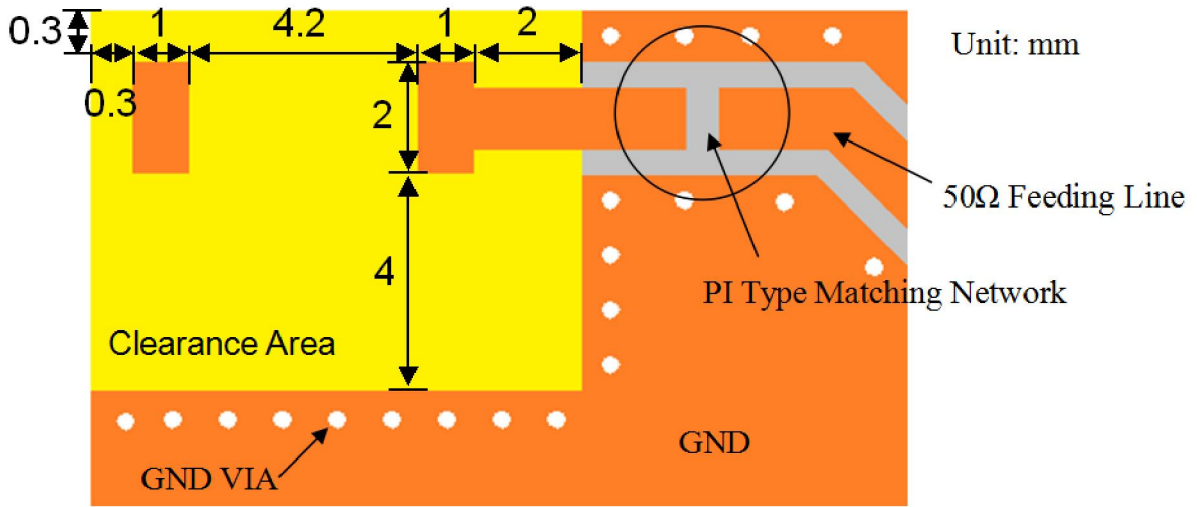
## 2. 型号 Part Number

LA 52 H 2450 - A36

|  |  |  |  |  |                                   |
|--|--|--|--|--|-----------------------------------|
|  |  |  |  |  |                                   |
|  |  |  |  |  | 产品名称, 编号 A36/Product Name: A36    |
|  |  |  |  |  | 天线频率/ Antenna Frequency: 2450 MHz |
|  |  |  |  |  | 产品设计结构 H 型/Via Design Series      |
|  |  |  |  |  | 产品尺寸/Size: 5.2×2.0×1.2            |
|  |  |  |  |  | 多层结构天线/Multi-layer Antenna        |

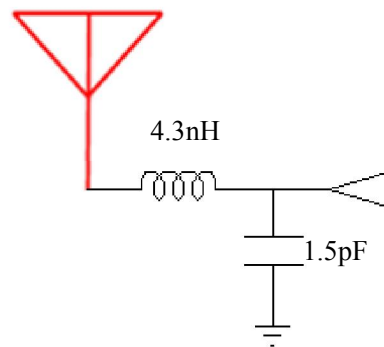
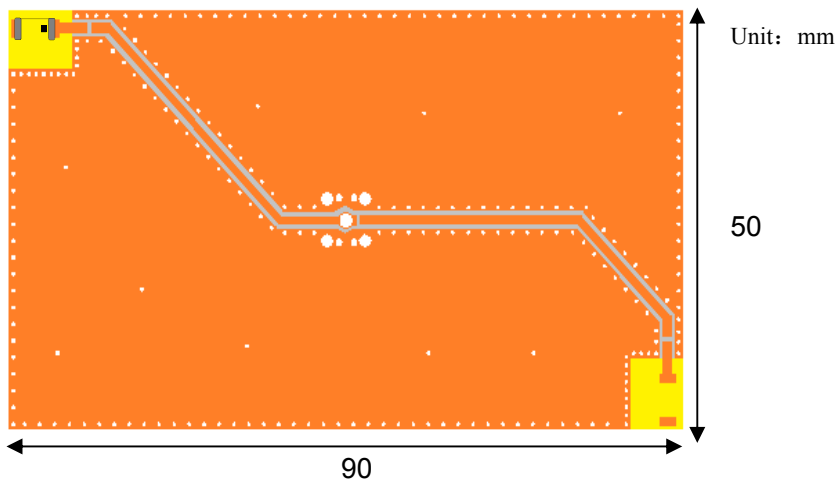
## 3.外型尺寸及测试板焊盘尺寸 Dimensions (Unit: mm)





4. 测试电路和匹配电路

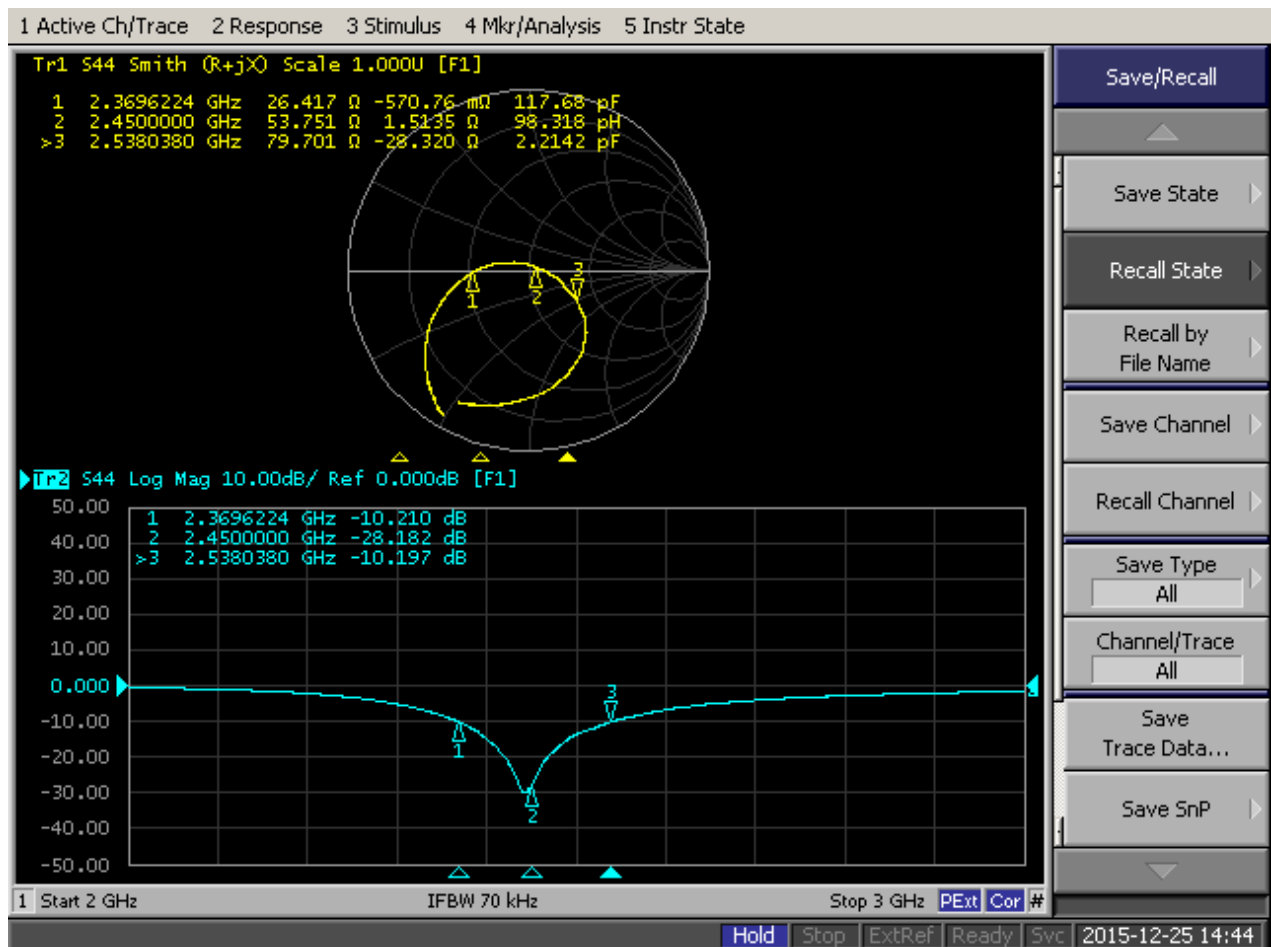
Evaluation Board and Matching Circuits



5. 电气性能 Electrical Characteristics

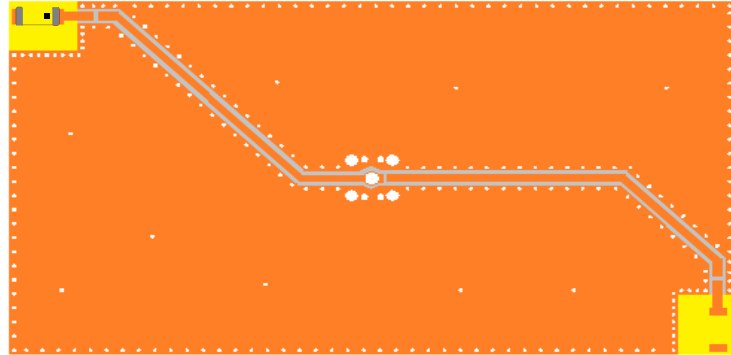
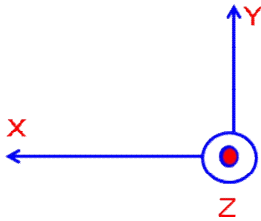
| No. | Item (项目)                        | Specifications (特性) |
|-----|----------------------------------|---------------------|
| 5.1 | Working Central Frequency 中心工作频率 | 2450 MHz            |
| 5.2 | Band Width 通带宽度                  | 100MHz typ.         |
| 5.3 | Peak Gain 峰值增益                   | 4.97 dBi            |
| 5.4 | V.S.W.R 驻波比                      | ≤2.0                |
| 5.5 | Polarization 极化方式                | Linear 线性           |
| 5.6 | Azimuth Beam width 方位角           | Omni-directional 全向 |
| 5.7 | Impedance 阻抗                     | 50 Ω                |

6. 特性曲线 Characteristic curve

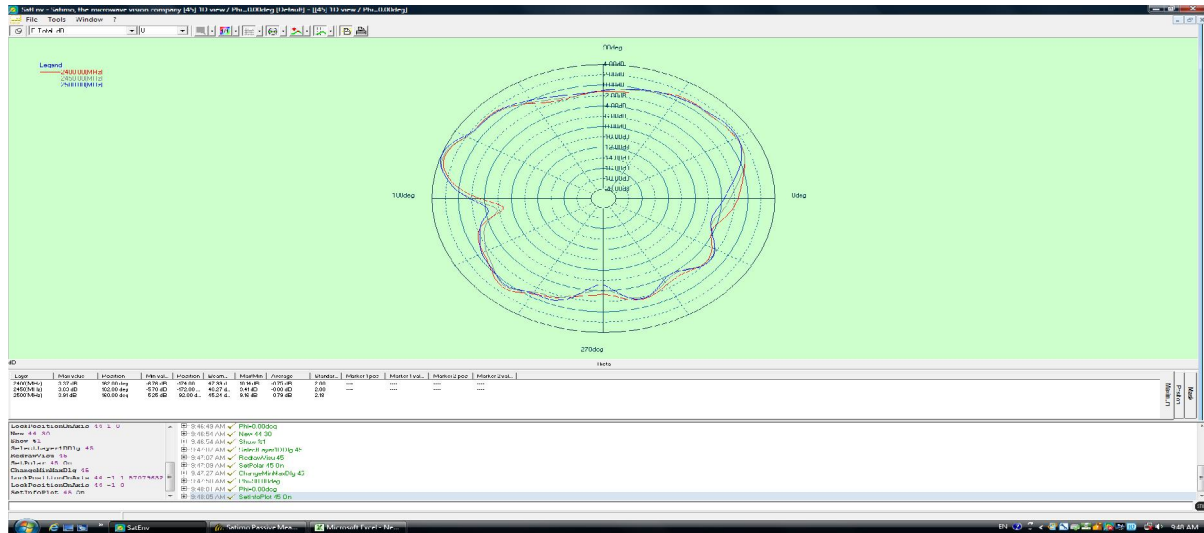


## 7. 方向图及效率 Radiation Pattern & Efficiency

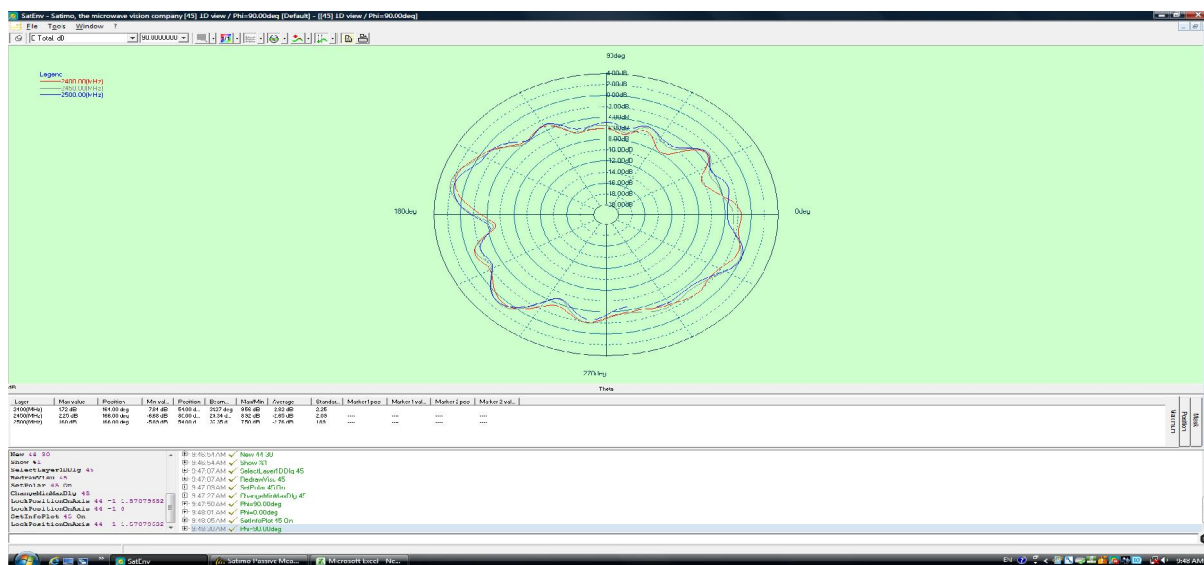
coordinates:



### X-Z Plane

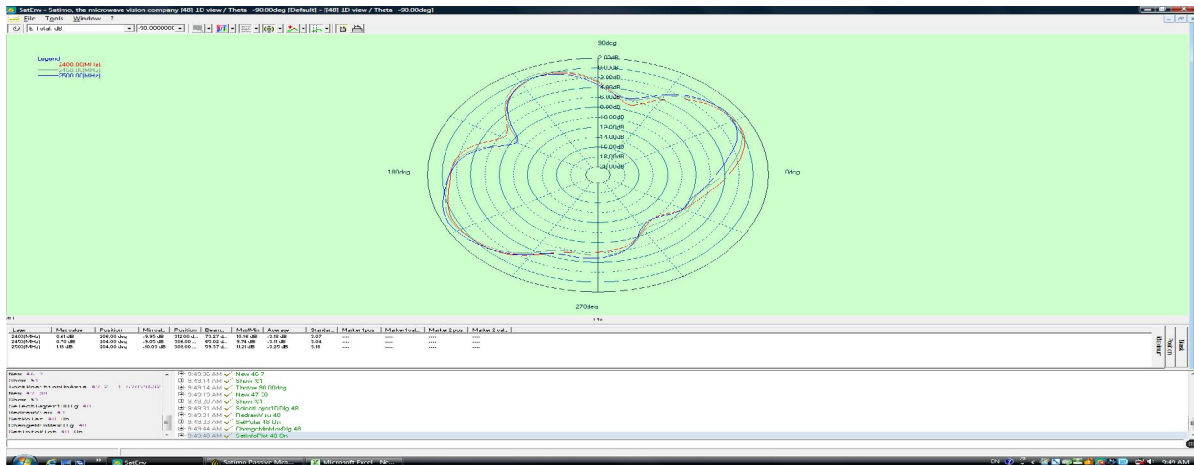


### Y-Z Plane

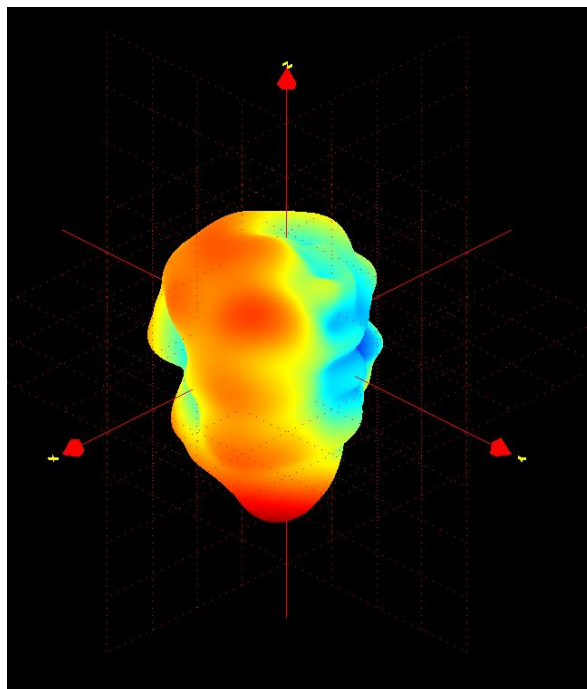




X-Y Plane



3D Radiation Pattern



|                 |       |       |       |
|-----------------|-------|-------|-------|
| Frequency (MHz) | 2400  | 2450  | 2500  |
| Avg. Gain (dBi) | -0.75 | -0.79 | -0.88 |
| Peck Gain (dBi) | 4.52  | 4.97  | 4.85  |
| Efficiency (%)  | 70.2  | 71.1  | 71.2  |

## 8 可靠性试验后允许误差 Post Dependability Tolerance

经可靠性试验后允许比起始读数偏差见下表

Post Dependability Tolerance (Refer to the table)

| No. | Item (项目)              | Post Dependability Tolerance<br>(可靠性试验后允许附加误差) |
|-----|------------------------|--|
| 8.1 | Central Frequency 中心频率 | ±5 MHz   |
| 8.2 | Band Width 通带宽度        | ±5 MHz   |
| 8.3 | Gain 增益                | ±0.1 dBi                                       |
| 8.4 | V.S.W.R (in BW) 驻波比    | ±0.1   |

## 9 可靠性试验 Dependability Test

|                                  |             |
|----------------------------------|-------------|
| 基准条件: 温度范围 Temperature range     | 25±5°C      |
| 相对湿度范围 Relative Humidity range   | 55~75%RH    |
| 工作温度 Operating Temperature range | -40°C~+85°C |
| 贮藏温度 Storage Temperature range   | -40°C~+85°C |

### 9.1 耐振动 Vibration Resist

在振动频率为 10~55Hz 振幅为 1.5mm 沿 X.Y.Z 方向各振动 2 小时后测试符合表 9.1~9.4 规定。

The device should satisfy the electrical characteristics specified in paragraph 9.1~9.4 after applied to the vibration of 10 to 55Hz with amplitude of 1.5mm for 2 hours each in X, Y and Z directions.

### 9.2 耐跌落冲击 Drop Shock

在 100cm 高度处按 X, Y, Z 三个面分别自由跌落在木制地板上共 3 次后测试符合表 9.1~9.4 规定。

The device should satisfy the electrical characteristics specified in paragraph 9.1~9.4 after dropping onto the hard wooden board from the height of 100cm for 3 times each facet of the 3 dimensions of the device.

### 9.3 耐焊接热 Solder Heat Proof

能承受经 120~150°C 的温度预热 120 秒后, 在 255°C+10°C 的焊锡浸 5±0.5 秒, 或 300°C-10°C 的电烙铁焊接 3±0.5 秒, 焊接面无损伤。

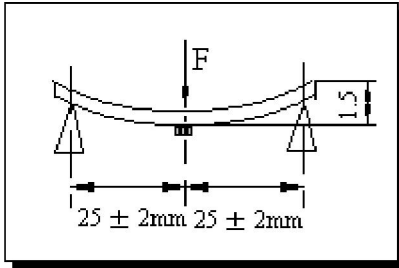
The device should be satisfied after preheating at 120°C~150°C for 120 seconds and dipping in soldering Sn at 255°C+10°C for 5±0.5 seconds, or electric iron 300°C-10°C for 3±0.5 seconds, without damnify.

### 9.4 结合力试验 Tensile Strength of Terminal

在产品电极端子上或表面上应能承受 1kg 垂直拉力 10±1 秒。

The device should not be broken after tensile force of 1.0kg is slowly applied to pull a lead pin of the fixed device in the lead axis direction for 10±1 seconds.

### 9.5 耐弯曲试验 Bending Resist Test



将产品按图焊在  $1.6 \pm 0.2\text{mm}$  的 PCB 板中间, 由箭头方向施力:  $1\text{mm/S}$ , 弯曲距离:  $1.5\text{mm}$ , 保持  $5 \pm 1\text{S}$ , 产品金属层无脱落。

Weld the product to the center part of the PCB with the thickness  $1.6 \pm 0.2\text{mm}$  as the illustration shows, and keep exerting force arrow-ward on it at speed of  $1\text{mm/S}$ , and hold for  $5 \pm 1\text{S}$  at the position of  $1.5\text{mm}$  bending distance, so far, any peeling off of the

product metal coating should not be detected.

### 9.6 耐湿热特性 Moisture Proof

在温度为  $60 \pm 2^\circ\text{C}$ , 相对湿度  $90\sim 95\%$  的恒温湿箱中放置 96 小时, 在常温中恢复 1~2 小时后测试, 符合表 9.1~9.4 规定。

The device should satisfy the electrical characteristics specified in paragraph 9.1~9.4 after exposed to the temperature  $60 \pm 2^\circ\text{C}$  and the relative humidity  $90\sim 95\%$  RH for 96 hours and 1~2 hours recovery time under normal condition.

### 9.7 高温特性 High Temperature Endurance

在温度为  $85 \pm 5^\circ\text{C}$  的恒温箱中放置  $96 \pm 2$  小时, 在常温中恢复 1~2 小时后测试。符合表 9.1~9.4 规定。

The device should satisfy the electrical characteristics specified in paragraph 9.1~9.4 after exposed to temperature  $85 \pm 5^\circ\text{C}$  for  $96 \pm 2$  hours and 1~2 hours recovery time under normal temperature.

### 9.8 低温特性 Low Temperature Endurance

在温度为  $-40^\circ\text{C} \pm 5^\circ\text{C}$  低温箱中放置  $96 \pm 2$  小时后恢复 1~2 小时测试符合表 9.1~9.4 规定。

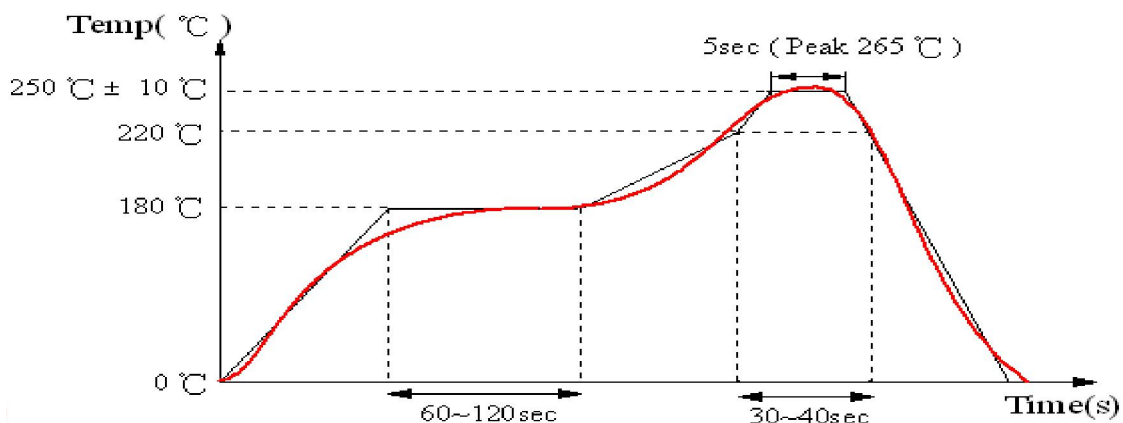
The device should also satisfy the electrical characteristics specified in paragraph 9.1~9.4 after exposed to the temperature  $-40^\circ\text{C} \pm 5^\circ\text{C}$  for  $96 \pm 2$  hours and to 2 hours recovery time under normal temperature.

### 9.9 温度循环 Temperature Cycle Test

在  $-40^\circ\text{C}$  温度中保持 30 分钟, 再在  $+85^\circ\text{C}$  温度中保持 30 分钟, 共循环 5 次后在常温中恢复 1~2 小时后测试符合表 9.1~9.4 规定。

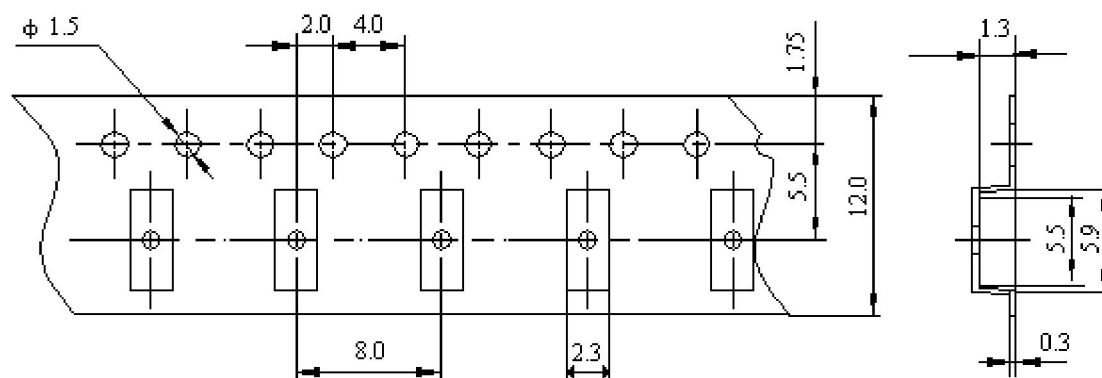
The device should also satisfy the electrical characteristics specified in paragraph 9.1~9.4 after exposed to the low temperature  $-40^\circ\text{C}$  and high temperature  $+85^\circ\text{C}$  for  $30 \pm 2$  min each by 5 cycles and 1 to 2 hours recovery time under normal temperature.

## 10 回流焊温度 Reflow Soldering Standard Condition



## 11 包装尺寸 (5220) Packaging and Dimensions

## 11.1 Plastic Tape

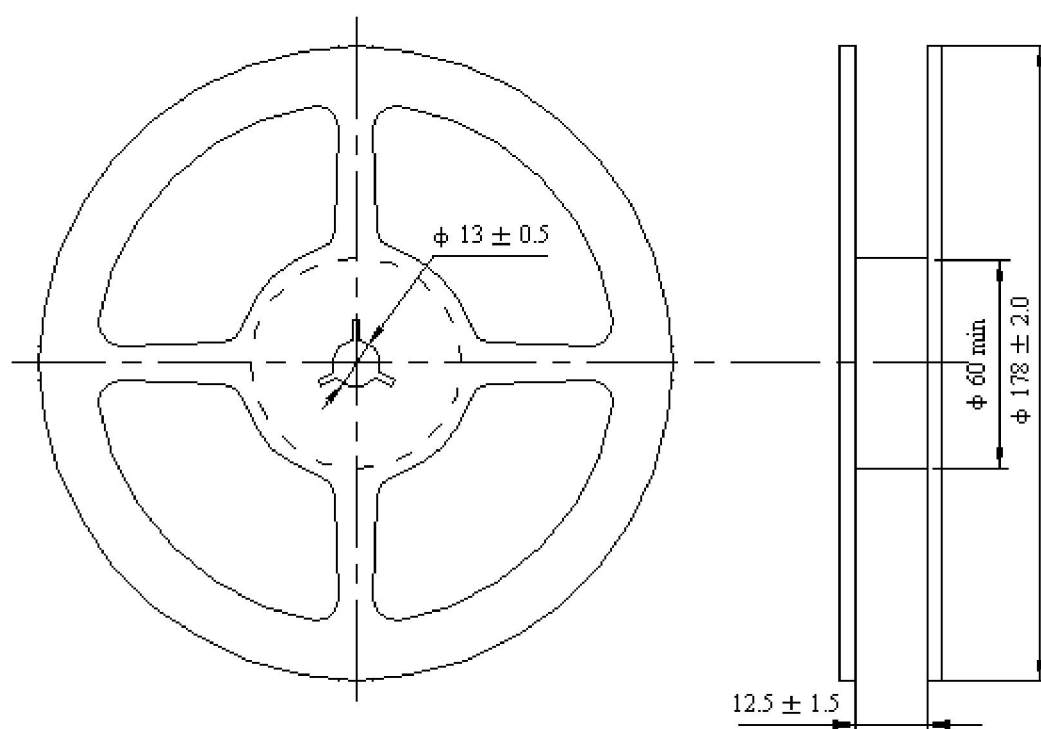


## 包装说明: Remarks for Package

载带尾部空穴长度 150~200mm, 载带头部空穴长度 250~300mm, 头部的盖带加长 250mm。

Reserve a length of 150~200mm for the trailer of the carrier and 250~300 mm for the leader of the carrier and further 250mm of cover tape at the leading part of the carrier.

## 11.2 Reel (1000 pcs/Reel)



## 11.3 储存条件 Storage Period

易氧化产品, 产品拆封后请于 48 小时内用完或重新密封包装!

Oxidizable. material, please repack within 48 hours by re-seal the package treatment after use them!